

Technical data sheet



Product: 601-T

Manufacturer: BOSTIK SA

Product group: KLEBSTOFF

Article group: 2-K KLEBSTOFF

Download: 06.10.2026

POLYTEC EP 601-T

This data sheet was provided to you by Tewipack Uhl GmbH. The company tewipack Uhl GmbH assumes no responsibility for the topicality and the Accuracy of the information contained. The properties of the products can vary due to various influences such as composition and condition of the Substrate, impurities in or on the substrate, temperature and humidity at the Change storage and environmental conditions during use. Using this product in combination with other material, the customer is responsible for to check through our own tests whether the product is suitable for the planned combination and whether this combination delivers the expected results

Tewipack Uhl GmbH
Industriestraße 15
D-75382 Althengstett

Telephone:
+49(0)7051/9297-0
Fax:
+49(0)7051/9297-99

E-Mail:
info@tewipack.de
Website:
www.tewipack.de

Managing director:
Alexander Uhl,
Michael Uhl
HRB 330424
Amtsgericht
Stuttgart

Bank details:
Sparkasse
Sindelfingen
Pforzheim
Calw
BLZ 666 500
85
Konto 17 787

Commerzbank
Sindelfingen
BLZ 603 400 71
Konto 8 001 166

Vereinigte
Volksbank AG
Böblingen
BLZ 603 900 00
Konto 80 089
003

Postbank
Stuttgart
BLZ 600 100
70
Konto 146
294 708

Polytec EP 601-T

Properties

Polytec EP 601-T is a transparent, two-component, thixotropic, non flowing epoxy adhesive which can be cured at room temperature.

Polytec EP 601-T is designed for applications in optics, fiber optics, optoelectronics, medical and semiconductor technology.

It has an excellent adhesion to glass, PMMA, quartz, silicon, ceramic, metals, FR 4, wood and most plastics.

The material can be applied via dispensing, jet-dispensing, potting and manual application.



Processing

- For two-component products the components A and B should be mixed carefully within the specified mixing ratio.
- For filled products both components should be homogenized carefully prior mixing, in order to prevent a possible settling of the filler.
- Processing should be carried out rapidly after mixing the components; as an indication the pot life can be used.
- Surfaces should be clean, thus free of dirt, grease, oil, dust or process chemicals.
- One-component products can be applied directly and are not subject to a pot life (except pre-mixed/frozen products).
- Please take notice of respective minimum curing temperature and time.
- For Safety information please refer to the respective Material Safety Data Sheet.

Polytec EP 601-T Unfilled Epoxy Adhesive Technical Data

Polytec EP 601-T

Properties in uncured state	Method	Unit	Technical Data
Chemical basis	-	-	Epoxy
No. of components	-	-	2
Mixing ratio (weight)	-	-	100:35
Mixing ratio (volume)	-	-	-
Pot life at 23°C	TM 702	h	4
Storage Stability at 23°C	TM 701	Months	12
Consistency	TM 101	-	Creamy Paste
Density Mix	TM 201.2	g/cm ³	1.05
Density A-Part	TM 201.2	g/cm ³	1.10
Density B-Part	TM 201.2	g/cm ³	0.90
Viscosity Mix 84 s ⁻¹ at 23°C	TM 202.1	mPa·s	3 000
Viscosity A-Part 84 s ⁻¹ at 23°C	TM 202.1	mPa·s	-
Viscosity B-Part 84 s ⁻¹ at 23°C	TM 202.1	mPa·s	-

Properties in cured* state	Method	Unit	Technical Data
Color	TM 101	-	Translucent
Hardness (Shore D)	DIN EN ISO 868	-	80
Temperature resistance continuous	TM 302	°C	-55 / +125
Temperature resistance short term	TM 302	°C	-55 / +220
Degradation Temperature	TM 302	°C	+280
Glass Transition Temperature (T _g)	TM 501	°C	>+65
Coefficient of thermal expansion (<T _g)	ISO 11359-2	ppm	-
Coefficient of thermal expansion (>T _g)	ISO 11359-2	ppm	-
Thermal conductivity	-	W/m·K	-
Elasticity modulus	TM 605	N/mm ²	3 500
Tensile Strength	TM 605	N/mm ²	65
Lap shear strength (Al/Al)	TM 604	N/mm ²	37
Elongation at break	TM 605	%	2.9
Water absorption 24 h, 23°C	TM 301	%	0.2

*The above data has been determined with samples cured at 150°C. Please notice, by varying the curing temperature these properties can be influenced to some extend.

Polytec EP 601-T

Curing*	Method	Unit	Technical Data
Minimum curing temperature		°C	15
Curing time at 23°C		h	16
Curing time at 80°C		min	90
Curing time at 100°C		min	40
Curing time at 120°C		min	-
Curing time at 150°C		min	12
Curing time at 180°C		s	-

*Curing temperatures refer to the temperature in the respective bond line. When choosing the respective curing conditions, the time needed to heat the substrate has to be considered. Depending on the type of heat source (convection oven, hot stamp, heating plate) the heat input may vary.

Standard pack sizes:

250 g, 500 g

1 kg

Customized packaging

Please note:

The above listed information are typical data based on tests and are believed to be accurate. Polytec PT makes no warranties (expressed or implied) as to their accuracy. The above listed data do not constitute specifications. The processing (in particular the cure conditions) of the material, the process control and the variety of different applications at various customers are not under Polytec PT's control. Therefore Polytec PT will not be liable for concrete results in any specific application or in any connection with the use of this product. In particular the cure conditions do have a major effect on the properties of the cured material. Therefore it is highly recommended to keep the cure schedule – once established - under tight control. With the release of this data sheet all former data sheets will be null and void.

Subject to alteration.

Polytec PT GmbH
Polymere Technologien
Ettlinger Straße 30
76307 Karlsbad
Germany
Tel. +49 (0) 7243 604-4000
Fax +49 (0) 7243 604-4200
info@polytec-pt.de
<http://www.polytec-pt.de>

Polytec France S.A.S.
TECHNOSUD II
Bâtiment A
99, Rue Pierre Semard
92320 Châtillon - France
Phone. +33 (0)1 49 65 69 00
Fax +33 (0)1 57 19 59 60
info@polytec.fr
<http://www.polytec-pt.com>

Polytec South-East Asia Pte Ltd
Blk 4010 Ang Mo Kio Ave 10
#06-06 Techplace I
Singapore 569626
Tel. +65 6451 0886
Fax +65 6451 0822
info@polytec-sea.com
<http://www.polytec-pt.com>